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FOAM-INSULATED WIRE

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Inventor: ISHIDO TAKAO; YAMAGUCHI TETSUO

Applicant: HIRAKAWA HEWTECH CORP

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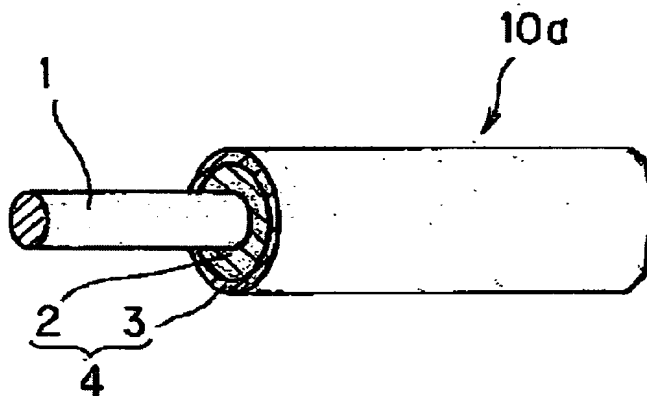
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Abstract of JP2001297633

PROBLEM TO BE SOLVED: To provide a foam-insulated wire, having low specific inductive capacity, exceedingly superior transmission characteristics and superior mechanical strength, such as tensile strength, compression resistance, and bending resistance, in which stabilities of transmission characteristics and mechanical strength are high, and which has satisfactory with respect to production efficiency, cost, and environmental friendliness. **SOLUTION:** A complex 4, in which a porous polyethylene layer 2 having a porosity of 80 or larger, which is made of a polyethylene whose weight average molecular weight is 5 million or larger, and a first polyester layer 3 are laminated, is wound around a conductor 1, such that the porous polyethylene layer 2 is on the conductor 1 side.

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